

ON Semiconductor®

FDB86363-F085

N-Channel PowerTrench® MOSFET **80 V, 110 A, 2.4 m** Ω

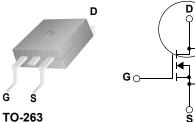
Features

- Typical $R_{DS(on)}$ = 2.0 m Ω at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{g(tot)}$ = 131 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems





MOSFET Maximum Ratings T_J = 25°C unless otherwise noted.

Symbol	Parameter	Ratings	Units		
V_{DSS}	Drain-to-Source Voltage		80	V	
V_{GS}	Gate-to-Source Voltage		±20	V	
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	110	A	
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	_ A	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	512	mJ	
D	Power Dissipation		300	W	
P_{D}	Derate Above 25°C		2.0	W/°C	
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.5	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W	

- 1: Current is limited by bondwire configuration.
- 2: Starting T_J = 25°C, L = 0.25mH, I_{AS} = 64A, V_{DD} = 80V during inductor charging and V_{DD} = 0V during time in avalanche.

 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB86363	FDB86363-F085	D2-PAK(TO-263)	330mm	24mm	800 units

Max.

Тур.

Min.

Units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted.

Parameter

Off Ch	aracteristics						
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$	V _{GS} = 0V	80	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =80V,	$T_J = 25^{\circ}C$	-	-	1	μΑ
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
less	Gate-to-Source Leakage Current	$V_{CS} = \pm 20 V$, ·	-	-	±100	nA

Test Conditions

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	2.0	2.4	mΩ
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	3.8	4.3	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 40V, V _{GS} = 0V, f = 1MHz		-	10000	-	pF
C _{oss}	Output Capacitance			-	1400	-	pF
C _{rss}	Reverse Transfer Capacitance			-	95	-	pF
R_g	Gate Resistance	f = 1MHz		-	3.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 64V	-	131	150	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		-	18	21	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	47	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	24	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	231	ns
t _{d(on)}	Turn-On Delay		-	38	-	ns
t _r	Rise Time	V _{DD} = 40V, I _D = 80A,	-	129	-	ns
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6Ω	-	64	-	ns
t _f	Fall Time		-	40	-	ns
t _{off}	Turn-Off Time		-	-	135	ns

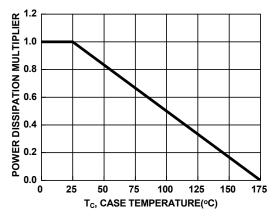
Drain-Source Diode Characteristics

V _{SD}	ISOURCE-TO-Drain Dione Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	٧
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	88	101	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =64V	-	129	157	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



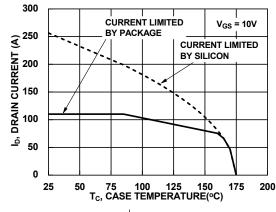
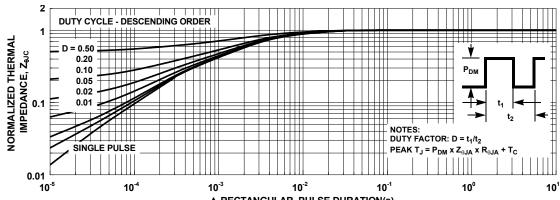


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

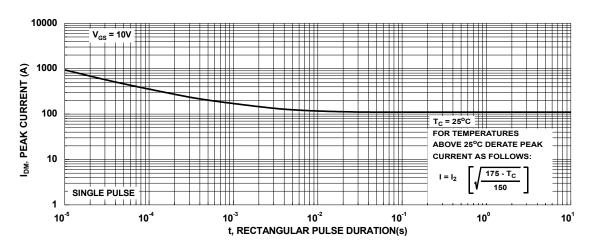


Figure 4. Peak Current Capability

Typical Characteristics

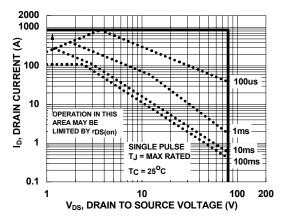


Figure 5. Forward Bias Safe Operating Area

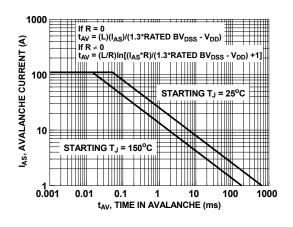


Figure 7. Transfer Characteristics

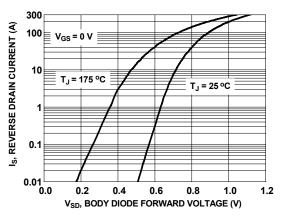


Figure 8. Forward Diode Characteristics

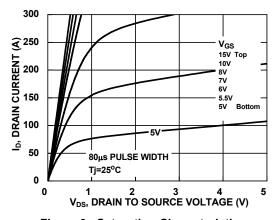


Figure 9. Saturation Characteristics

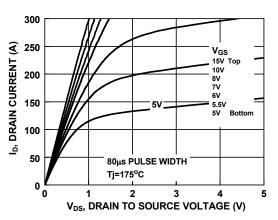


Figure 10. Saturation Characteristics

Typical Characteristics

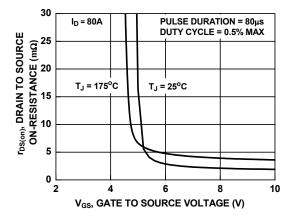


Figure 11. R_{DSON} vs. Gate Voltage

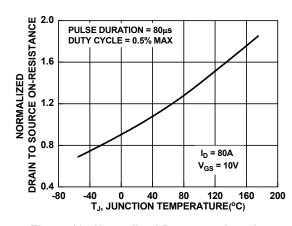


Figure 12. Normalized R_{DSON} vs. Junction Temperature

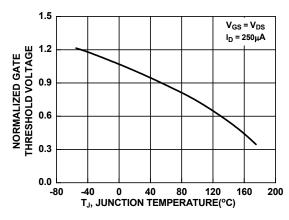


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

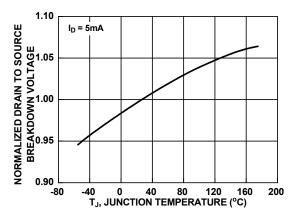


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

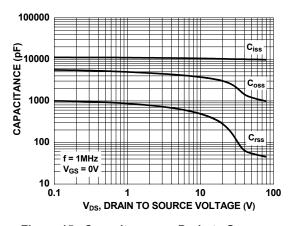


Figure 15. Capacitance vs. Drain to Source Voltage

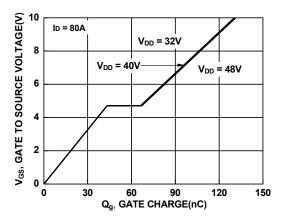


Figure 16. Gate Charge vs. Gate to Source Voltage

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